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- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
   Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

#### **E OR M PACKAGE** (TOP VIEW) 1A $V_{CC}$ 1B 🛮 2 13 4B 1Y 🛮 3 12 4A 11 4Y 2A 2B 10 3B 2Y 🛮 9 3A 6 3Y GND

#### description/ordering information

The CD74AC86 is a quadruple 2-input exclusive-OR gate. This device performs the Boolean function  $Y = A \oplus B$  or  $Y = \overline{AB} + A\overline{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

#### ORDERING INFORMATION

TA	PACKA	GE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – E	Tube	CD74AC86E	CD74AC86E	
-55°C to 125°C	SOIC - M	Tube	CD74AC86M	AC86M	
	OOIO IVI	Tape and reel	CD74AC86M96		

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

# FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L



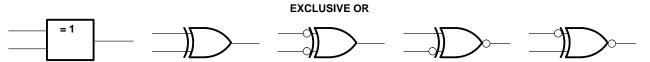
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#### exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an CD74AC86 gate in positive logic; negation may be shown at any two ports.

# The output is active (low) if all inputs stand at the same logic level (i.e., A = B). EVEN-PARITY ELEMENT 2k 2k + 1 The output is active (low) if an even number of inputs (i.e., on 2) are active. The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	$\dots$ -0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): E package	80°C/W
M package	86°C/W
Storage temperature range, T <sub>stg</sub>	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



### recommended operating conditions (see Note 3)

			T <sub>A</sub> = 25°C			–55°C to 125°C		–40°C to 85°C		
			MIN	MAX	MIN	MAX	MIN	MAX		
Vсс	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V	
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2			
٧ıH	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		2.1		2.1		V	
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85			
		V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3		
VIL	Low-level input voltage	V <sub>CC</sub> = 3 V		0.9		0.9		0.9	V	
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65		
٧ <sub>I</sub>	Input voltage		0	VCC	0	VCC	0	VCC	V	
۷o	Output voltage		0	VCC	0	VCC	0	VCC	V	
ІОН	High-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		-24		-24		-24	mA	
loL	Low-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		24		24		24	mA	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 1.5 \text{ V to 3 V}$		50		50		50	ns/V	
ΔψΔV	Input transition rise or fall rate	$V_{CC} = 3.6 \text{ V to } 5.5 \text{ V}$		20		20		20	115/V	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	VCC	T <sub>A</sub> = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX	
			1.5 V	1.4		1.4		1.4		
		$I_{OH} = -50  \mu A$	3 V	2.9		2.9		2.9		
			4.5 V	4.4		4.4		4.4		
Voн	VI = VIH or VIL	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V
		I <sub>OH</sub> = -24 mA	4.5 V	3.94		3.7		3.8		
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85				
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3.85		
			1.5 V		0.1		0.1		0.1	
		I <sub>OL</sub> = 50 μA	3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
$V_{OL}$	VI = VIH or VIL	I <sub>OL</sub> = 12 mA	3 V		0.36		0.5		0.44	V
		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44	
		I <sub>OL</sub> = 50 mA <sup>†</sup> 5.5 V				1.65				
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65	
lį	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND,	I <sub>O</sub> = 0	5.5 V		4		80		40	μΑ
C <sub>i</sub>					10		10		10	pF

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



## CD74AC86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATE

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 1.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40°C TO 85°C		UNIT	
	(1141 01)	(6611 61)	MIN	MAX	MIN	MAX		
tPLH	A or B	V		135		123		
<sup>t</sup> PHL	A or B	ſ		135		123	ns	

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3 V $\pm$ 0.3 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C TO 85°C		UNIT
	(1141 01)	(6611 61)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	V	3.8	15.1	3.9	13.7	
<sup>t</sup> PHL	A or B	r	3.8	15.1	3.9	13.7	ns

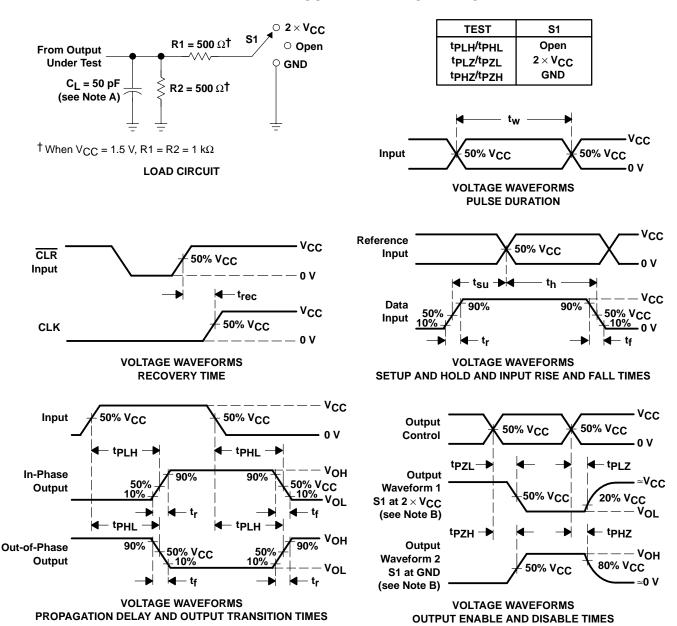
# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C TO 85°C		UNIT
	(1141 01)	(6611 61)	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	V	2.7	10.8	2.8	9.8	no
<sup>t</sup> PHL	A or B	ī	2.7	10.8	2.8	9.8	ns

## operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	57	pF

#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 3 \ ns$ ,  $t_f = 3 \ ns$ . Phase relationships between waveforms are arbitrary.
  - D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
  - E. The outputs are measured one at a time with one input transition per measurement.
  - F. tpLH and tpHL are the same as tpd.
  - G. tpzL and tpzH are the same as ten.
  - H. tpLz and tpHz are the same as tdis.
  - I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
CD74AC86E	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74AC86E
CD74AC86E.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74AC86E
CD74AC86M	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-55 to 125	AC86M
CD74AC86M96	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC86M
CD74AC86M96.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC86M

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC86M9	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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#### \*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	CD74AC86M96	SOIC	D	14	2500	353.0	353.0	32.0

# **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74AC86E	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC86E	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC86E.A	N	PDIP	14	25	506	13.97	11230	4.32
CD74AC86E.A	N	PDIP	14	25	506	13.97	11230	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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